

Exhibit C

Semiconductor Terminology

Graphic Glossary of Terms

Michael Heynes, Ph.D.
Anne K. Miller

**Based on "Microchip Fabrication –
A Practical Guide to Semiconductor Processing"
By Peter Van Zant**

Published By:
Semiconductor Services
735 Hillcrest Way
Redwood City
California 94062 U.S.A.
Phone (650) 369-7890 Fax (650) 367-1062
E-Mail info@semiconductorservices.com

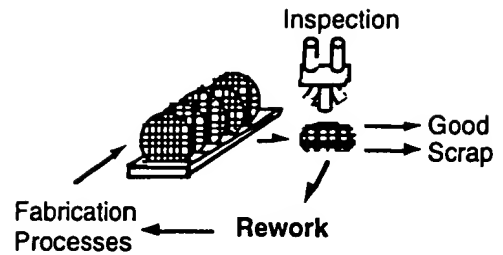
Copyright Semiconductor Services 1999
Third Edition 1999
ISBN Number 1-887574-02-6

All Rights Reserved. No part of this publication may be reproduced, stored in a retrieval system, or transmitted in any form or by any means, electronic, mechanical, photocopying, recording, or otherwise, without the prior written consent of the publisher.

Printed in the United States of America

REWORK:

Out-of-specification wafers that are sent through a process again.

**REWORK RATE:**

The percentage of wafers requiring rework.

Rework Rate =

$$\frac{\# \text{ Reworked Wafers}}{\# \text{ Wafers started in process step}} \times 100 \%$$

RF:

See "Radio Frequency".

RF HEATING:

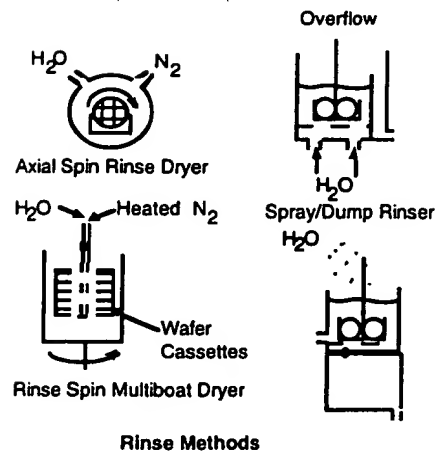
See "Radio Frequency Heating".

RIE:

See "Reactive Ion Etch".

RINSE:

The removal of cleaning solutions, etchants or developers etc. from the wafer using water. This process stops the processes by removing the active chemical from the surface. There are several different methods of rinsing: overflow rinsing, dump rinsing, and spin/rinse drying.



Rinse Methods